

| L Number | Hits | Search Text | DB | Time stamp |
|----------|---------|--|---|---------------------|
| 1 | 27408 | tape with carrier | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/09/29 09:34 |
| 2 | 68781 | tcp (tape with carrier with (package packaged packaging)) (tape with carrier) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/09/29 09:36 |
| 3 | 2598502 | semiconductor die dice chip ic (integrated adj circuit) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/09/29 09:37 |
| 4 | 1426855 | leadframe lead (lead adj frame) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/09/29 09:37 |
| 5 | 9959 | (tcp (tape with carrier with (package packaged packaging)) (tape with carrier)) and (semiconductor die dice chip ic (integrated adj circuit)) and (leadframe lead (lead adj frame)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/09/29 09:38 |
| 6 | 3301 | (tcp (tape with carrier with (package packaged packaging)) (tape with carrier)) same (semiconductor die dice chip ic (integrated adj circuit)) same (leadframe lead (lead adj frame)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/09/29 09:39 |
| 7 | 415339 | (leadframe lead (lead adj frame)) and (trace land pad electrode) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/09/29 09:39 |
| 8 | 609711 | (leadframe lead (lead adj frame)) and (trace land pad terminal electrode) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/09/29 09:39 |
| 9 | 2291 | ((tcp (tape with carrier with (package packaged packaging)) (tape with carrier)) same (semiconductor die dice chip ic (integrated adj circuit)) same (leadframe lead (lead adj frame))) and (trace land pad terminal electrode) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/09/29 09:40 |
| 10 | 6781 | ((tcp (tape with carrier with (package packaged packaging)) (tape with carrier)) and (semiconductor die dice chip ic (integrated adj circuit)) and (leadframe lead (lead adj frame))) and (trace land pad terminal electrode) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/09/29 09:40 |
| 11 | 1184 | ((((tcp (tape with carrier with (package packaged packaging)) (tape with carrier)) same (semiconductor die dice chip ic (integrated adj circuit)) same (leadframe lead (lead adj frame))) and (trace land pad terminal electrode)) and (bga ball bump) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/09/29 09:40 |